CHEMENCE
CREATING BONDS THAT LAST

KD1092-TDS-R1

Revision Date: 2022-07-11

KE1092

Product Description:

Krylex® KE1092 is a one component heat cure epoxy adhesive designed for bonding components in the assembly of electronic devices. The product offers excellent adhesion to low surface energy plastics e.g. poly carbonate (PC) and metals at low process assembly temperatures. Rapid cure at temperatures over 80°C.

Product Features

- One Component
- Rapid cure @ +80C
- Thixotropic

UNCURED PROPERTY	VALUE	METHOD
Technology	Epoxy	N/A
Appearance	White/Yellow	N/A
Cure	Heat	30 min @ 100^{0}C
Viscosity cP	11,200	@25^{0}C, 1.0rpm
Viscosity cP	3,820	@25^{0}C, 10.0rpm
Thixotropic Index	2.93	

CURED PROPERTY	VALUE	TEST METHOD
Hardness	80	SHORE D
Tg	43	°C/DSC
Lap Shear	13.9	SUS-SUS / MPa
Lap Shear	7.5	PCGF -PCGF / MPa

General Information

For safe handling of this product consult the Safety Data Sheet**.**

Note: KE1092 reacts quickly when exposed to temperatures above 80^{0}C. The product evolves heave (exotherms) during the solidification reaction.

Handling and Safety

For maximum shelf life, keep containers sealed and store in dry conditions. Keep out of the reach of children. Uncured adhesive contains free isocyanates and it' s very important to follow the safety and handling guidelines. Use heat resistant gloves for handling hot syringes. Appropriate eye wear and protective equipment is required during the usage of uncured material. Refer to SDS for further information.

NOTES

All the test data, recommended procedures and other statements contained herein are furnished for information only for this experimental material and accuracy of the information is not guaranteed. Chemence cannot assume responsibility for the results obtained by others over whose methods we have no control. It is the user's responsibility to determine suitability for the user's purpose of any production methods mentioned herein and to adopt such precautions as may be advisable for the protection of property and of persons against any hazards that may be involved in the handling and use thereof. Considering the foregoing, Chemence specifically disclaims all warranties expressed or implied, including warranties of merchantability or fitness for a particular purpose, arising from sale or use of Chemence' s products. Chemence specifically disclaims any liability for consequential or incidental damages of any kind, including lost profits. The discussion herein of various processes or compositions is not to be interpreted as representation that they are free from domination of patents owned by others or as a license under any Chemence patents that may cover such processes or compositions. We recommend that each prospective user test his proposed application before repetitive use, using this data as a guide. This product may be covered by one or more United States or foreign patents or patent application